SPECIFICATION

DEVICE NAME : Power MOSFET

TYPE NAME : 2SK2833-R

SPEC. No. :

Fuji Electric Co.,Ltd.
Matsumoto Factory

This Specification is subject to change without notice.

	DATE	NAME	APPROVED		Fuji Electric Co.,Ltd.
DRAWN					
CHECKED				DWG.NO.	1/10

1. Scope
This specifies Fuji power MOSFET 2SK2833-R

2. Construction N-channel enhancement mode power MOSFET

3. Application for switching

4. Outview TO-3PF Outview See to 4/10 page

5. Absolute maximum ratings at Tc=25℃ (unless otherwise specified)

Description	Symbol	Characteristics	Unit	
Drain-source voltage	V_{DS}	120	V	
Drain-gate voltage	V_{DGR}	120	V	R_{GS}=20kΩ
Continuous Drain current	I_D	± 50	A	
Pulsed drain current	I_{Dpulse}	± 200	A	
Gate-source voltage	V_{GS}	± 20	V	
Maximum power dissipation	P_D	100	W	
Operating and storage temperature range	T_{ch}	150	℃	
	T_{stg}	-55 ~ +150	℃	

6. Electrical characteristics at Tc=25℃ (unless otherwise specified)
Static ratings

Description	Symbol	Conditions		Characteristics			Unit
				Min.	Typ.	Max.	
Drain-source breakdown voltage	BV_{DSS}	I_D=1mA V_{GS}=0V		120			V
Gate threshold voltage	$V_{GS(th)}$	I_D=1mA V_{DS}=V_{GS}		1.0	1.5	2.5	V
Zero gate voltage drain current	I_{DSS}	V_{DS}=120V V_{GS}= 0V	T_{ch}= 25℃		10	500	μA
	I_{DSS}		T_{ch}=125℃		0.2	1.0	mA
Gate-source leakage current	I_{GSS}	V_{GS}=±20V V_{DS}= 0V			10	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	I_D=25A	V_{GS}= 4V		25	45	mΩ
			V_{GS}=10V		20	30	

Dynamic ratings

Description	Symbol	Conditions	Characteristics			Unit
			Min.	Typ.	Max.	
Forward transconductance	gfs	I_D = 25A V_{DS}= 25V	25	50		S
Input capacitance	Ciss	V_{DS}=25V V_{GS}= 0V f =1MHz		5000	7500	pF
Output capacitance	Coss			920	1380	pF
Reverse transfer capacitance	Crss			500	750	pF
Turn-on time	td(on)	V_{CC}= 60V V_{GS}= 10V I_D = 50A R_{GS}= 25Ω		30	45	ns
	tr			200	300	ns
Turn-off time	td(off)			950	1425	ns
	tf			400	600	ns

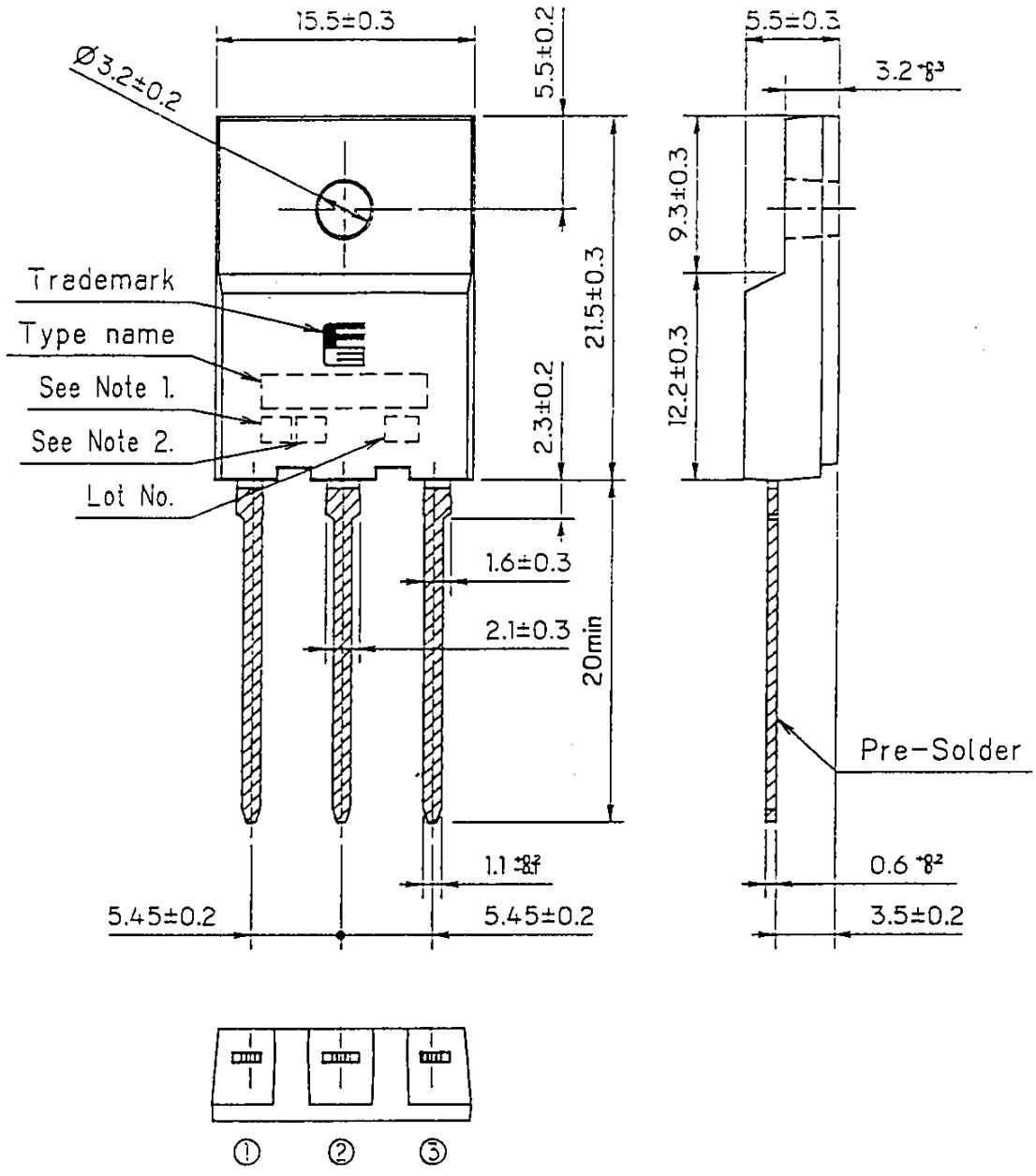
Reverse diode

Description	Symbol	Conditions	Characteristics			Unit
			Min.	Typ.	Max.	
Diode forward on-voltage	V_{SD}	I_F = 2 × I_{DR} V_{GS}=0V, T_{ch}=25℃		1.33	2.0	V
Reverse recovery time	t_{rr}	I_F = I_{DR} V_{GS}=0V $-dI_F/dt$=100A/μs T_{ch}=25℃		150		ns
Reverse recovery charge	Q_{rr}			1.1		μC

7. Thermal resistance

Description	Symbol	Conditions	Characteristics			Unit
			Min.	Typ.	Max.	
Thermal resistance	$R_{th(ch-c)}$				1.25	℃/W
	$R_{th(ch-a)}$				30	℃/W

FUJI POWER MOSFET



CONNECTION

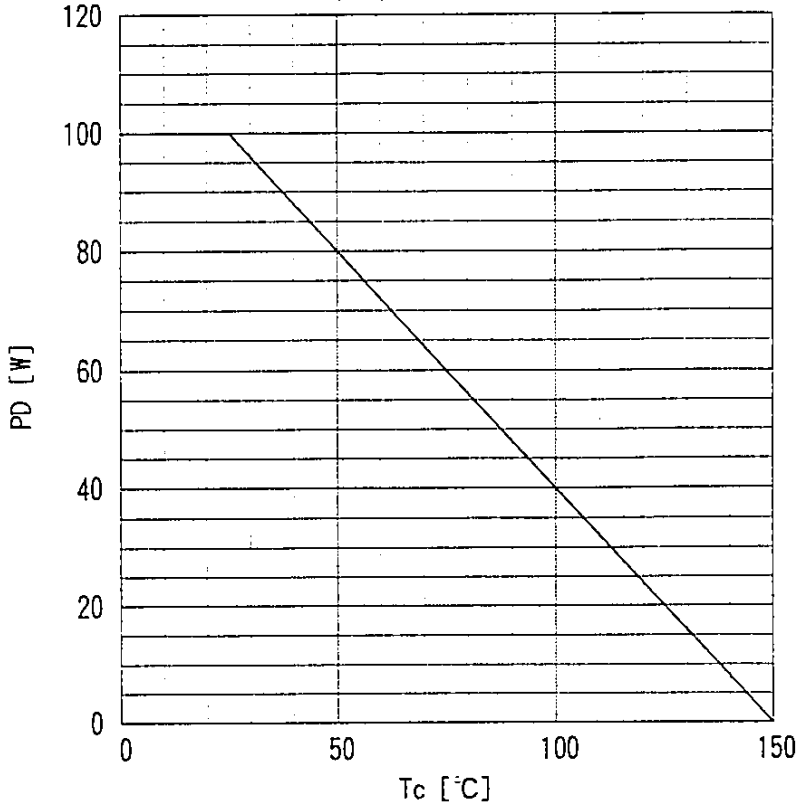
Note 1. Guaranteed mark of avalanche ruggedness.

2. $V_{GS(th)}$ selected code.

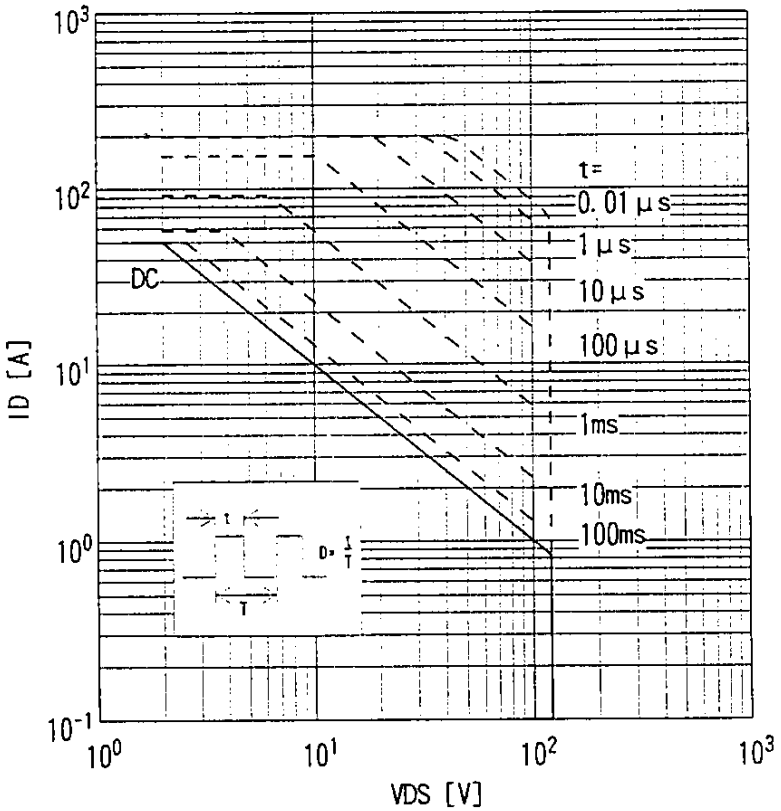
① GATE
② DRAIN
③ SOURCE

DIMENSIONS ARE IN MILLIMETERS.

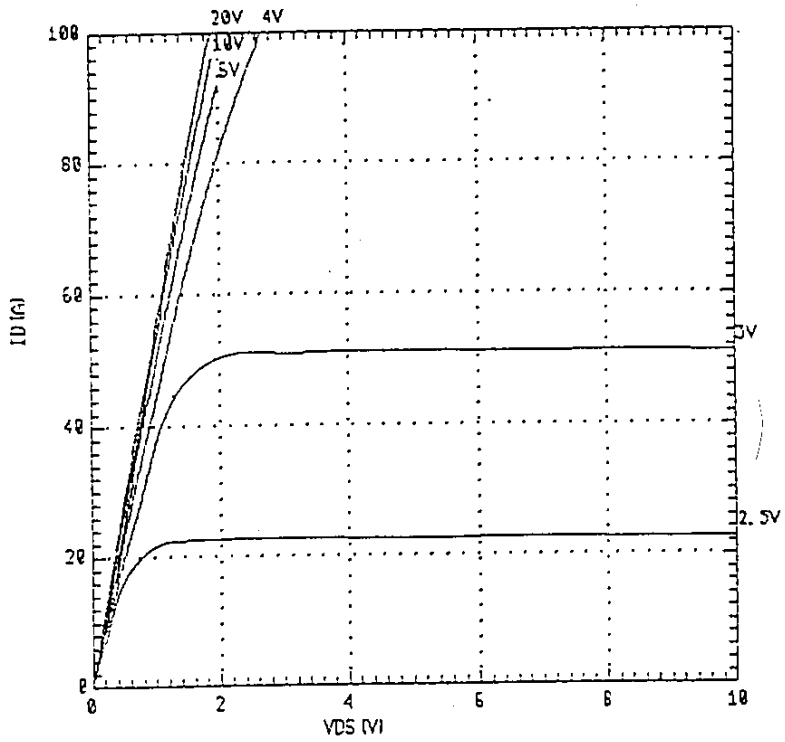
Power Dissipation
PD=f(Tc)



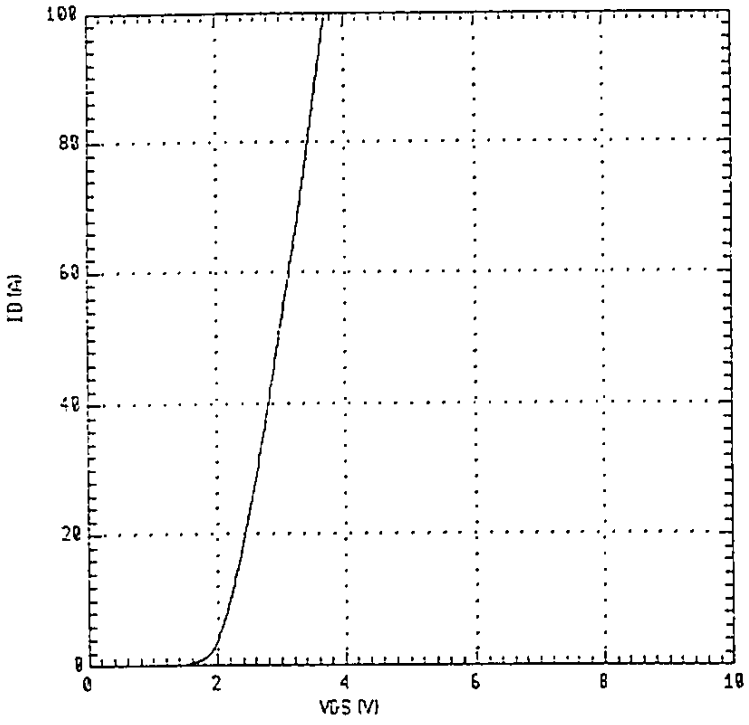
Safe operating area
ID=f(VDS):D=0.01, Tc=25°C



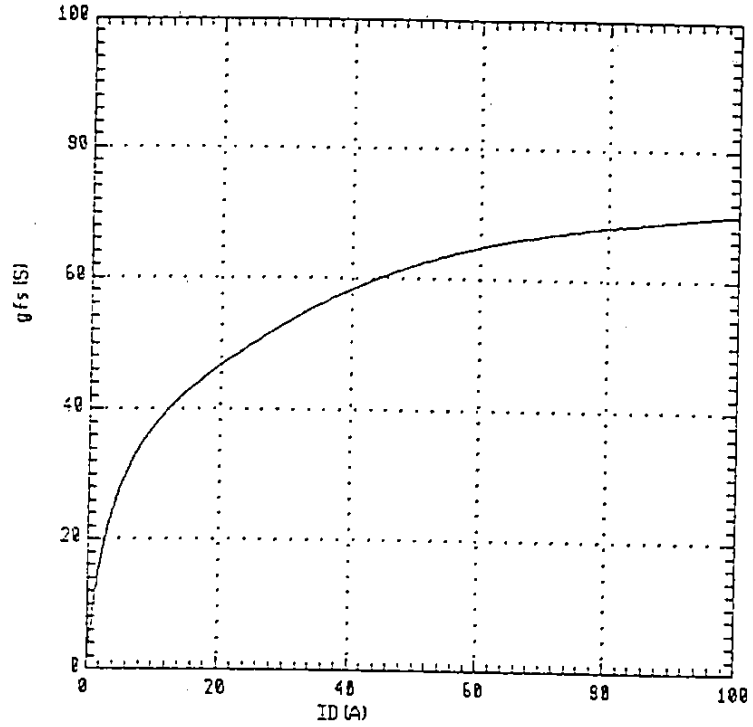
Typical output characteristics
ID=f(VDS):80μs pulse test,Tch=25°C



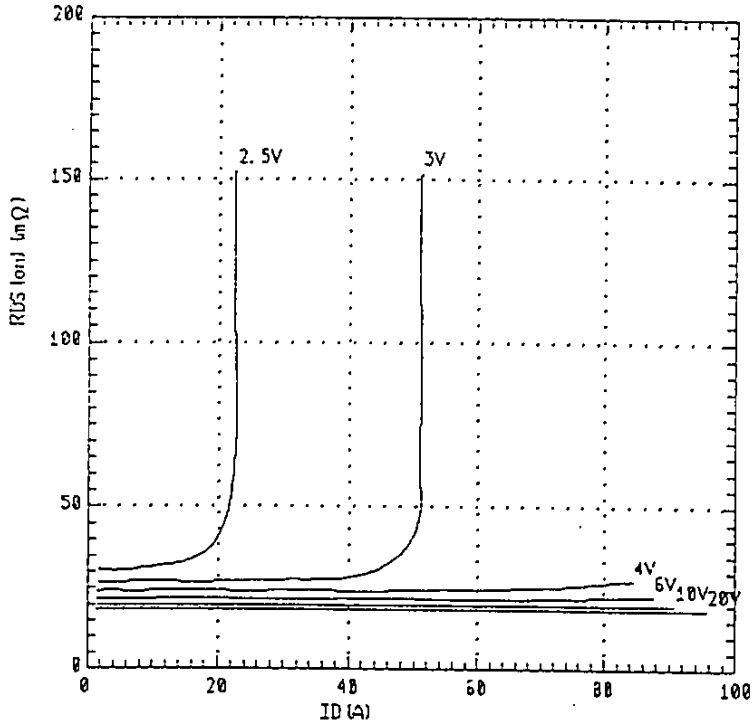
Typical Transfer Characterisic
ID=f(VGS):80μs pulse test,VDS=25V



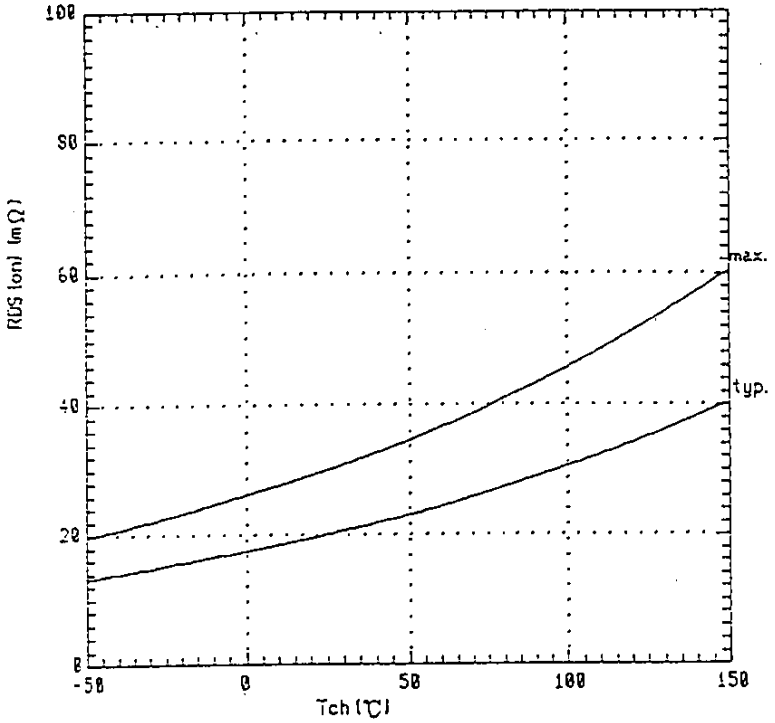
Typical Transconductance
gfs=f(ID):80μs pulse test,VDS=25V,Tch=25℃



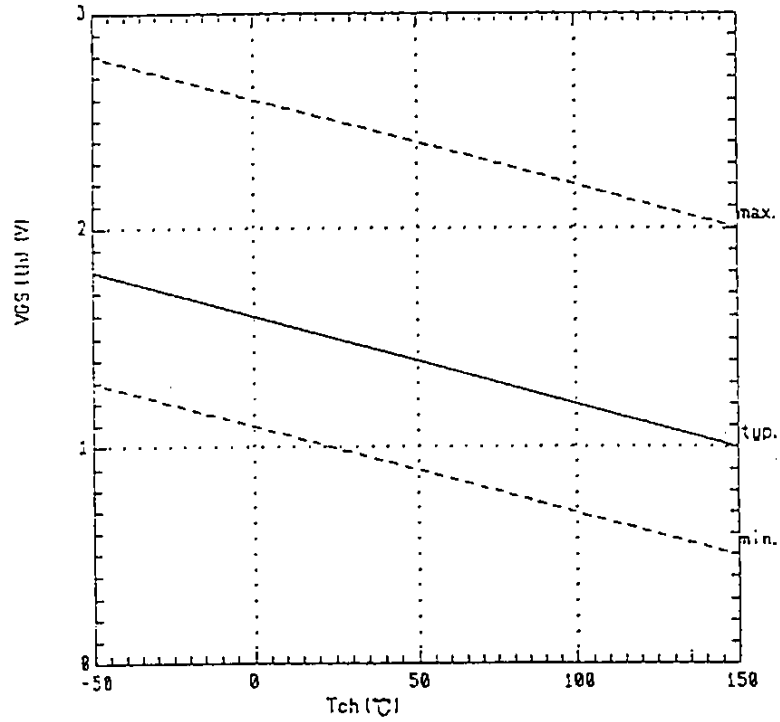
Typical Drain-source on-state resistance
RDS(on)=f(ID):80μs pulse test,Tch=25℃



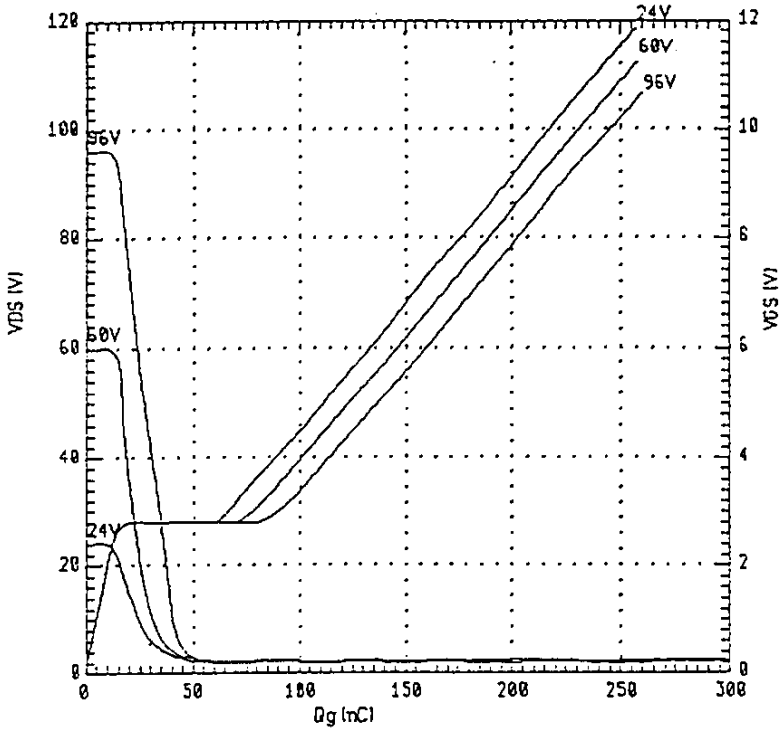
Drain-source on-state resistanse
RDS(on)=f(Tch):ID=25A,VGS=10V



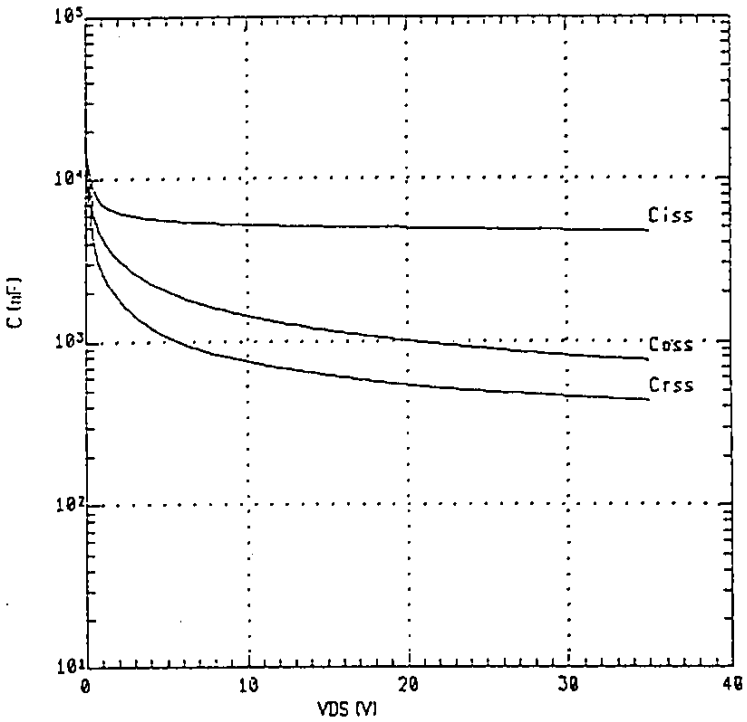
Gate threshold voltage
VGS(th)=f(Tch):VDS=VGS,ID=1mA



Typical gate charge characteristics
VGS=f(Qg):ID=50A

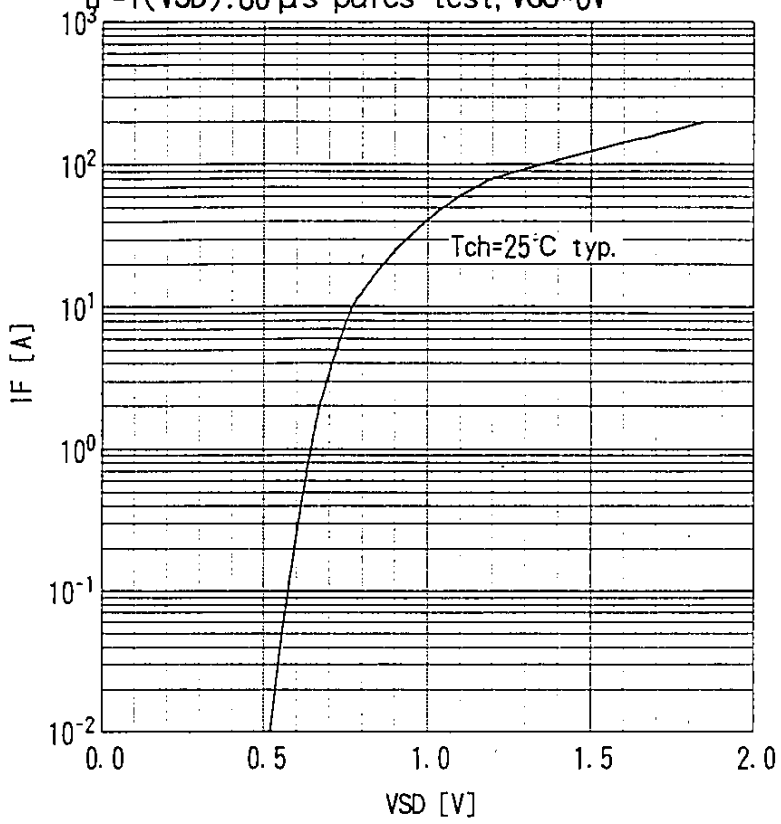


Typical capacitances
C=f(VDS):VGS=0V, f=1MHz



Forward characteristic of reverse of diode

IF=f(VSD):80 μs pules test, VGS=0V



Transient thermal impedande

Zthch=f(t) parameter:D=t/T